

1 Characteristics

Table 2. Absolute ratings (limiting values, per diode, at $T_{amb} = 25\text{ °C}$ unless otherwise specified)

Symbol	Parameter				Value	Unit
V _{RRM}	Repetitive peak reverse voltage				80	V
I _{F(RMS)}	Forward rms current				30	A
I _{F(AV)}	Average forward current, δ = 0.5	TO-220AB, I ² PAK, D ² PAK	T _C = 155 °C T _C = 150 °C	Per diode Per device	10 20	A
		TO-220FPAB	T _C = 130 °C T _C = 100 °C	Per diode Per device	10 20	
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms sinusoidal		T _C = 25 °C	220	A
P _{ARM} ⁽¹⁾	Repetitive peak avalanche power		T _j = 25 °C, t _p = 1 μs		5400	W
V _{ARM} ⁽²⁾	Maximum repetitive peak avalanche voltage	t _p < 1 μs, T _j < 150 °C, I _{AR} < 16.2 A			100	V
V _{ASM} ⁽²⁾	Maximum single pulse peak avalanche voltage	t _p < 1 μs, T _j < 150 °C, I _{AR} < 16.2 A			100	V
T _{stg}	Storage temperature range				-65 to +175	°C
T _j	Maximum operating junction temperature ⁽³⁾				175	°C

1. For temperature or pulse time duration deratings, please refer to figure 3 and 4. More details regarding the avalanche energy measurements and diode validation in the avalanche are provided in the application notes AN1768 and AN2025.

2. See [Figure 13](#)

3. $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal parameters

Symbol	Parameter			Value	Unit
$R_{th(j-c)}$	Junction to case	TO-220AB	per diode	2.30	°C/W
		I ² PAK, D ² PAK	total	1.55	
		TO-220FPAB	per diode	5.80	
			total	4.65	
$R_{th(c)}$	Coupling	TO-220AB I ² PAK, D ² PAK		0.80	°C/W
		TO-220FPAB		3.50	

When the two diodes 1 and 2 are used simultaneously:

$$\Delta T_j(\text{diode 1}) = P(\text{diode 1}) \times R_{th(j-c)}(\text{Per diode}) + P(\text{diode 2}) \times R_{th(c)}$$

Table 4. Static electrical characteristics (per diode)

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ }^\circ\text{C}$	$V_R = V_{RRM}$	-	5.8	25	μA
		$T_j = 125\text{ }^\circ\text{C}$		-	5	15	mA
$V_F^{(2)}$	Forward voltage drop	$T_j = 25\text{ }^\circ\text{C}$	$I_F = 5\text{ A}$	-	0.590	0.640	V
		$T_j = 125\text{ }^\circ\text{C}$		-	0.515	0.550	
		$T_j = 25\text{ }^\circ\text{C}$	$I_F = 10\text{ A}$	-	0.710	0.780	
		$T_j = 125\text{ }^\circ\text{C}$		-	0.595	0.650	
		$T_j = 25\text{ }^\circ\text{C}$	$I_F = 20\text{ A}$	-	0.850	0.945	
		$T_j = 125\text{ }^\circ\text{C}$		-	0.690	0.780	

1. Pulse test: $t_p = 5\text{ ms}$, $\delta < 2\%$ 2. Pulse test: $t_p = 380\text{ }\mu\text{s}$, $\delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 0.52 \times I_{F(AV)} + 0.013 \times I_{F(RMS)}^2$$

Figure 2. Average forward power dissipation versus average forward current (per diode)

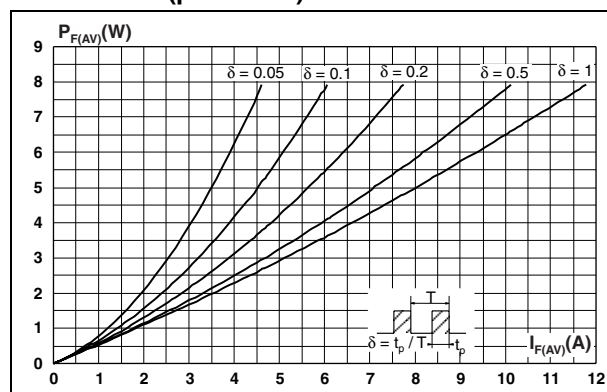
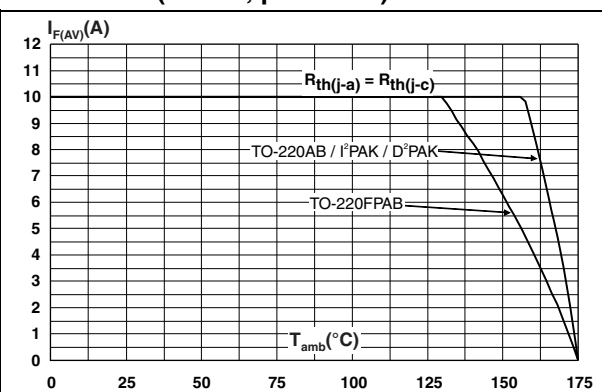
Figure 3. Average forward current versus ambient temperature ($\delta = 0.5$, per diode)

Figure 4. Normalized avalanche power derating versus pulse duration

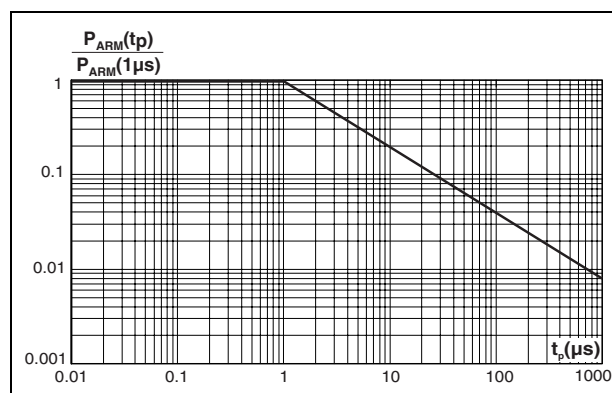


Figure 5. Normalized avalanche power derating versus junction temperature

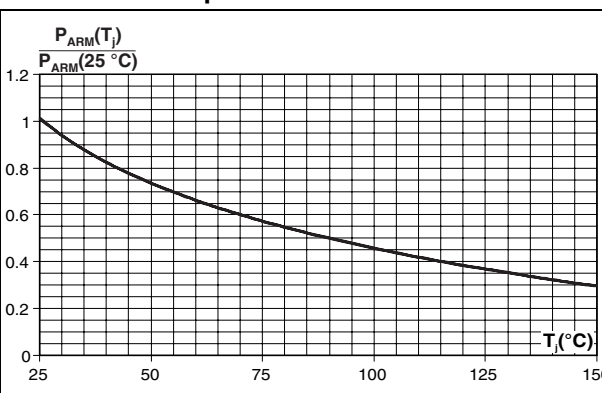


Figure 6. Non repetitive surge peak forward current versus overload duration (maximum values, per diode)

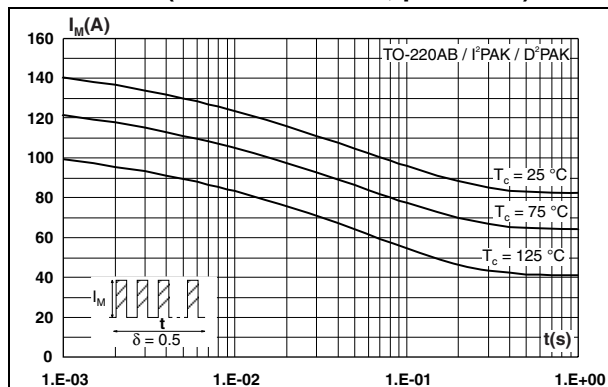


Figure 7. Non repetitive surge peak forward current versus overload duration (maximum values, per diode)

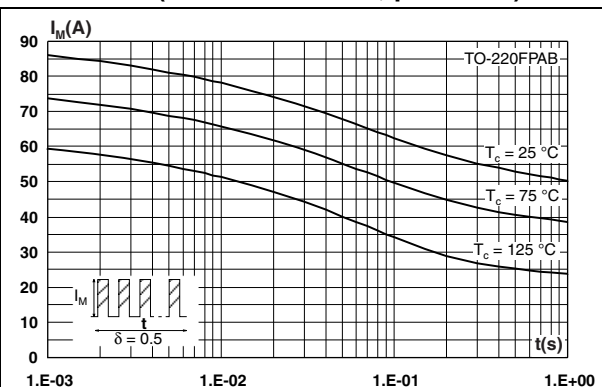


Figure 8. Relative thermal impedance junction to case versus pulse duration

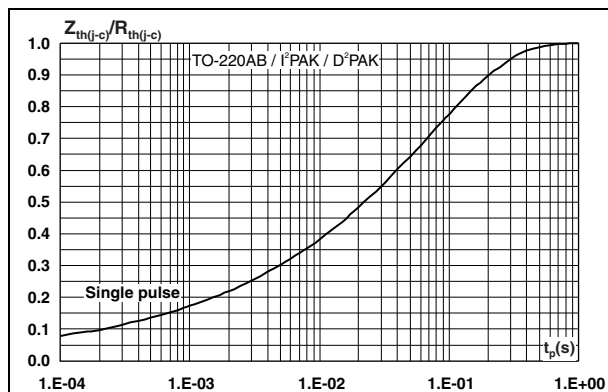


Figure 9. Relative thermal impedance junction to case versus pulse duration (TO-220FPAB)

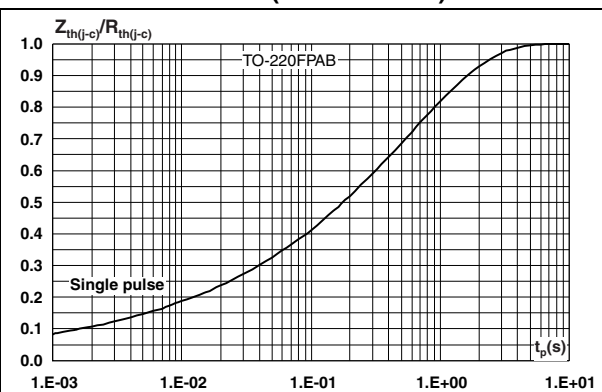


Figure 10. Reverse leakage current versus reverse voltage applied (typical values, per diode)

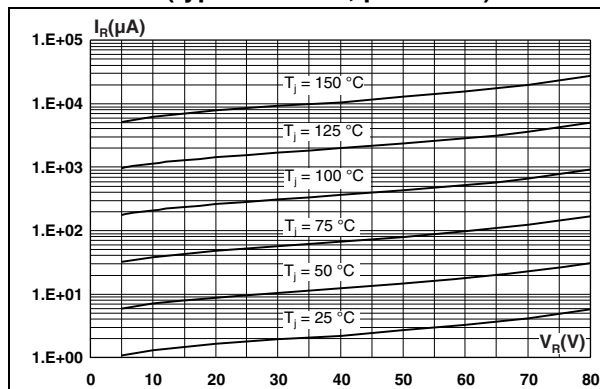


Figure 11. Junction capacitance versus reverse voltage applied (typical values, per diode)

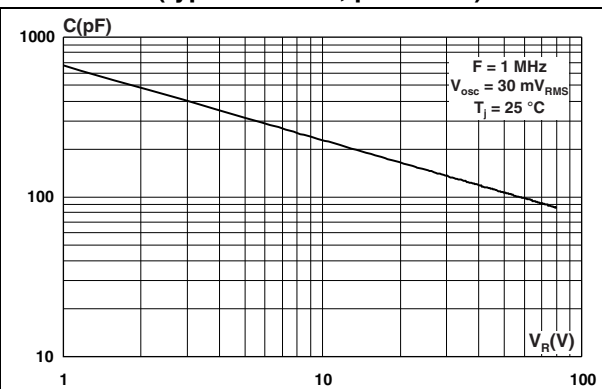


Figure 12. Forward voltage drop versus forward current (per diode)

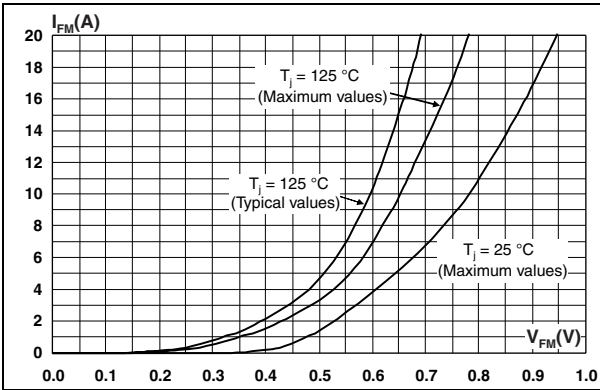


Figure 13. Reverse safe operating area ($t_p < 1\text{ }\mu\text{s}$ and $T_j < 150\text{ }^{\circ}\text{C}$)

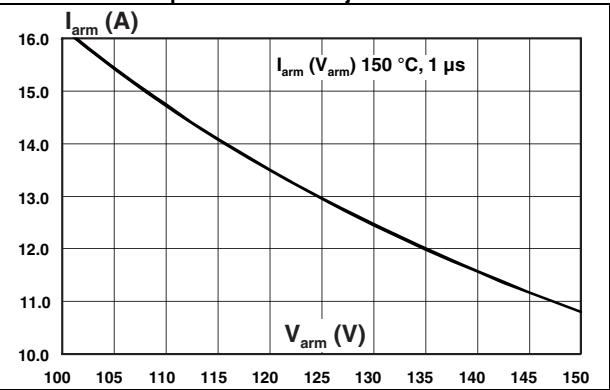
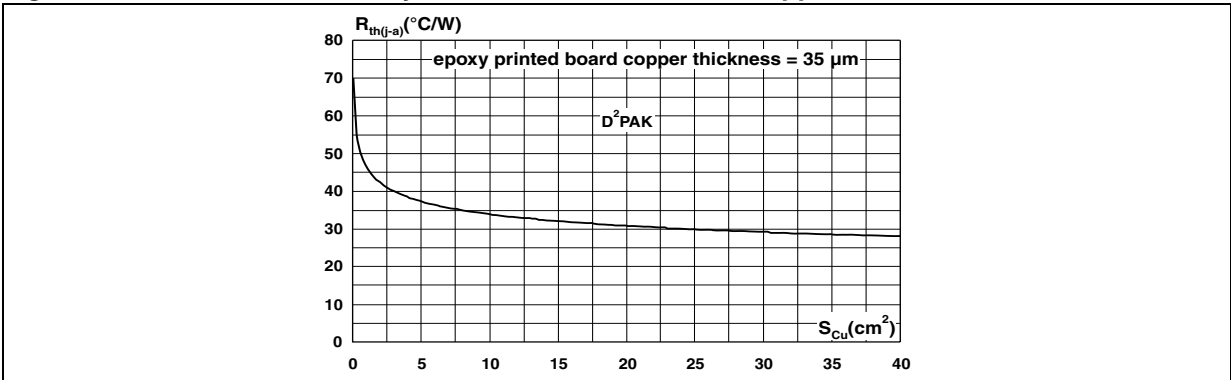


Figure 14. Thermal resistance junction to ambient versus copper surface under tab for D²PAK



2 Package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.4 to 0.6 N·m

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

Table 5. TO-220AB dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
F2	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
G1	2.40	2.70	0.094	0.106
H2	10	10.40	0.393	0.409
L2	16.4 Typ.		0.645 Typ.	
L4	13	14	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.6 Typ.		0.102 Typ.	
Dia.	3.75	3.85	0.147	0.151

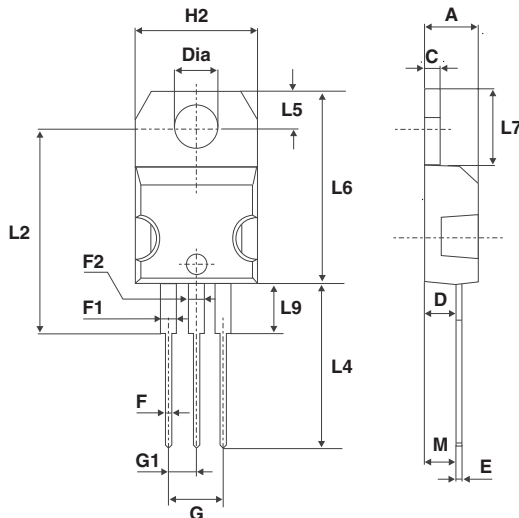
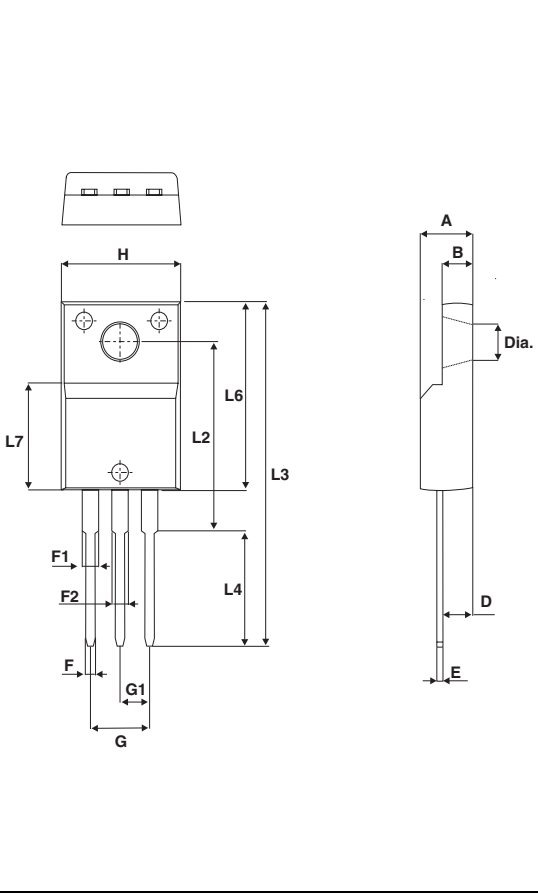


Table 6. TO-220FPAB dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.4	4.9	0.173	0.192
B	2.5	2.9	0.098	0.114
D	2.45	2.75	0.096	0.108
E	0.4	0.7	0.016	0.028
F	0.6	1	0.024	0.039
F1	1.15	1.7	0.045	0.067
F2	1.15	1.7	0.045	0.067
G	4.95	5.2	0.195	0.205
G1	2.4	2.7	0.094	0.106
H	10	10.7	0.394	0.421
L2	16 Typ.		0.630 Typ.	
L3	28.6	30.6	1.126	1.205
L4	9.8	10.7	0.386	0.421
L6	15.8	16.4	0.622	0.646
L7	9	9.9	0.354	0.390
Dia.	2.9	3.5	0.114	0.138



The technical drawing illustrates the TO-220FPAB package from three perspectives: top, side, and lead views. The top view shows a rectangular body with a central circular feature and four mounting holes. Dimensions A through H and L2, L3, L4, L6, L7 are indicated. The side view shows the profile of the package with dimensions A, B, D, and E. The lead view shows the leads with dimensions F, F1, F2, G, and G1. A diameter dimension (Dia.) is also shown for the lead thickness.

Table 7. D²PAK dimensions

Technical drawing of a 100mm x 100mm x 10mm plate. The drawing includes a top view, a front view, and a side view. Dimensions are labeled as follows:

- Top View:** L (Total Length), L2 (Distance from top edge to center of hole), L3 (Distance from center of hole to bottom edge), E (Total Width), B (Distance from center of hole to side edge), B2 (Distance from center of hole to side edge).
- Front View:** A (Total Height), C2 (Distance from top edge to center of hole), D (Distance from center of hole to bottom edge), R (Radius of fillet), A1 (Angle of fillet), C (Distance from center of hole to side edge).
- Side View:** A2 (Distance from top edge to center of hole), M (Distance from center of hole to side edge), V2 (Angle of fillet).

* FLAT ZONE NO LESS THAN 2mm

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
A2	0.03	0.23	0.001	0.009
B	0.70	0.93	0.027	0.037
B2	1.14	1.70	0.045	0.067
C	0.45	0.60	0.017	0.024
C2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
E	10.00	10.40	0.393	0.409
G	4.88	5.28	0.192	0.208
L	15.00	15.85	0.590	0.624
L2	1.27	1.40	0.050	0.055
L3	1.40	1.75	0.055	0.069
M	2.40	3.20	0.094	0.126
R	0.40 typ.		0.016 typ.	
V2	0°	8°	0°	8°

Figure 15. D²PAK footprint (dimensions in mm)

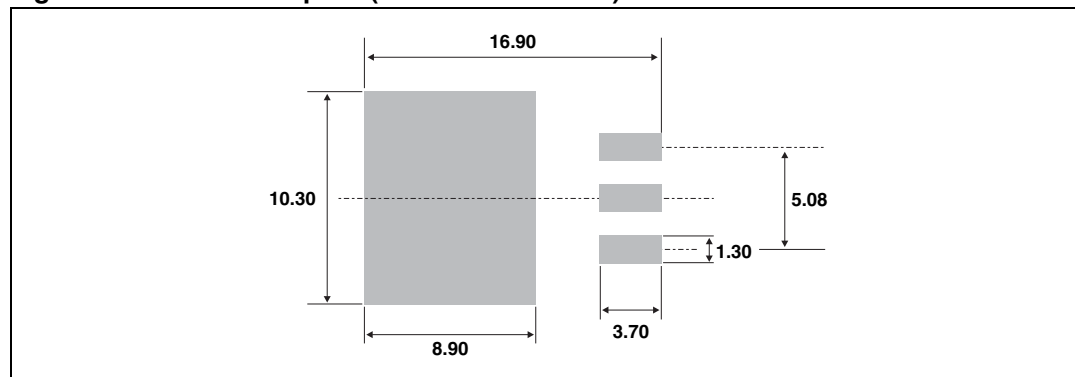


Table 8. I²PAK dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.40	2.72	0.094	0.107
b	0.61	0.88	0.024	0.035
b1	1.14	1.70	0.044	0.067
c	0.49	0.70	0.019	0.028
c2	1.23	1.32	0.048	0.052
D	8.95	9.35	0.352	0.368
e	2.40	2.70	0.094	0.106
e1	4.95	5.15	0.195	0.203
E	10	10.40	0.394	0.409
L	13	14	0.512	0.551
L1	3.50	3.93	0.138	0.155
L2	1.27	1.40	0.050	0.055

3 Ordering information

Table 9. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS20SM80CT	PS20SM80CT	TO-220AB	1.9 g	50	Tube
STPS20SM80CFP	PS20SM80CFP	TO-220FPAB	2.0 g	50	Tube
STPS20SM80CR	PS20SM80CR	I ² PAK	1.49 g	50	Tube
STPS20SM80CG-TR	PS20SM80CG	D ² PAK	1.48 g	1000	Tape and reel

4 Revision history

Table 10. Revision history

Date	Revision	Changes
11-Apr-2011	1	First issue.

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